

APPLICABLE STANDARD						
RATING	OPERATING TEMPERATURE RANGE	-35°C TO +85 °C (NOTES 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C (NOTE3)		
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTES 2)	STORAGE HUMIDITY RANGE	40 % TO 70 % (NOTE3)		
	CURRENT	1 A	VOLTAGE	150 V AC (DC)		
SPECIFICATIONS						
ITEM		TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION						
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	X	X
MARKING		CONFIRMED VISUALLY.			X	X
ELECTRIC CHARACTERISTICS						
CONTACT RESISTANCE		20mV MAX , 1 m A (DC OR 1000 Hz).		30 mΩ MAX.	X	-
INSULATION RESISTANCE		100 V DC.		500 MΩ MIN.	X	-
VOLTAGE PROOF		500 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	X	-
MECHANICAL CHARACTERISTICS						
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			X	-
ENVIRONMENTAL CHARACTERISTICS						
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 → 5 TO 35 → +85 → 5 TO 35 °C TIME 30 → 5 MAX → 30 → 5 MAX min UNDER 5 CYCLES.		① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			X	-
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING «REFLOW AREA» MAX250°C WITHIN 10 sec MIN 230°C WITHIN 60 sec «PREHEATING AREA» 170°C to 190°C 60 sec to 120 sec PUT THROUGH IN REFLOW FUMACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350 ± 5°C, SOLDERING TIME : 5 ± 1sec. NO STRENGTH ON CONTACT.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	-
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 235 ± 5°C FOR INSERTION DURATION, 3sec.		SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMersed.	X	-
REMARKS						
NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT						
NOTE2:NO CONDENSING						
NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD. AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION Unless otherwise specified, refer to JIS C 5402.						
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE	
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				APPROVED	TY.OMA	06.07.22
				CHECKED	HK.UMEHARA	06.07.22
				DESIGNED	TS.KUMAZAWA	06.07.22
				DRAWN	TS.KUMAZAWA	06.07.22
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-160331-05	
SPECIFICATION SHEET			PART NO.	DF14-2P-1. 25H (90)		
HIROSE ELECTRIC CO., LTD.			CODE NO.	CL538-0021-4-90	△	1/1